



PRELIMINARY

T-46-13-25

NMC27C512AN 524,288-Bit (64k x 8) One Time Programmable CMOS PROM

General Description

The NMC27C512AN is a high-speed 512k UV one time programmable CMOS EPROM, ideally suited for applications where fast turnaround and low power consumption are important requirements.

The NMC27C512AN is designed to operate with a single +5V power supply with $\pm 5\%$ or $\pm 10\%$ tolerance. The CMOS design allows the part to operate over extended and military temperature ranges.

The NMC27C512AN is packaged in a 28-pin dual-in-line plastic molded package without a transparent lid. This part is ideally suited for high volume production applications where cost is an important factor and programming only needs to be done once. Also the plastic molded package works well in auto insertion equipment used in automated assembly lines.

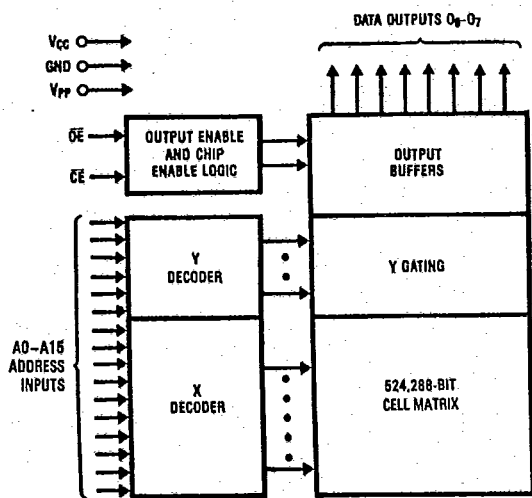
This EPROM is fabricated with National's proprietary, time proven CMOS double-poly silicon gate technology which combines high performance and high density with low power consumption and excellent reliability.

Features

- Clocked sense amps for fast access time down to 150 ns
- Low CMOS power consumption
 - Active Power: 110 mW max
 - Standby Power: 0.55 mW max
- Optimum EPROM for total CMOS systems
- Pin compatible with NMOS 512k EPROMs
- Fast and reliable programming —100 μ s typical/byte
- Static operation—no clocks required
- TTL, CMOS compatible inputs/outputs
- TRI-STATE[®] output
- Manufacturer's Identification code for automatic programming control
- High current CMOS level output drivers

NMC27C512AN

Block Diagram



TL/D/8754-1

Pin Names

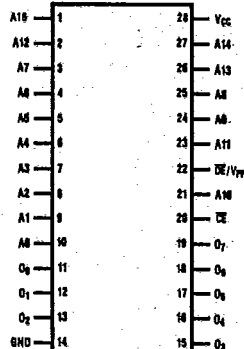
A0-A15	Addresses
\overline{CE}	Chip Enable
\overline{OE}/V_{PP}	Output Enable/Programming Voltage
O0-O7	Outputs
PGM	Program
NC	No Connect

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Connection Diagram

27C256 27256	27C128 27128	27C64 2764	27C32 2732	27C16 2716
V _{PP}	V _{PP}	V _{PP}		
A12	A12	A12		
A7	A7	A7	A7	A7
A6	A6	A6	A6	A6
A5	A5	A5	A5	A5
A4	A4	A4	A4	A4
A3	A3	A3	A3	A3
A2	A2	A2	A2	A2
A1	A1	A1	A1	A1
A0	A0	A0	A0	A0
O ₀	O ₀	O ₀	O ₀	O ₀
O ₁	O ₁	O ₁	O ₁	O ₁
O ₂	O ₂	O ₂	O ₂	O ₂
GND	GND	GND	GND	GND

NMC27C512AN
Dual-In-Line Package

27C16 2716	27C32 2732	27C64 2764	27C128 27128	27C256 27256
V _{CC}	V _{CC}	V _{CC} PGM	V _{CC} PGM	V _{CC}
A8	A8	A8	A8	A8
A9	A9	A9	A9	A9
V _{PP}	A11	A11	A11	A11
OE	OE/V _{PP}	OE	OE	OE
A10	A10	A10	A10	A10
OE/V _{PP}	OE	OE	OE	OE
O ₇	O ₇	O ₇	O ₇	O ₇
O ₈	O ₈	O ₈	O ₈	O ₈
O ₅	O ₅	O ₅	O ₅	O ₅
O ₄	O ₄	O ₄	O ₄	O ₄
O ₃	O ₃	O ₃	O ₃	O ₃

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Order Number NMC27C512AN
See NS Package Number N28B

Note: Socket compatible EPROM pin configurations are shown in the blocks adjacent to the NMC27C512AN pins.

Commercial Temp Range (0°C to +70°C)

V_{CC} = 5V ± 5%

Parameter/Order Number	Access Time (ns)
NMC27C512AN15	150
NMC27C512AN17	170
NMC27C512AN20	200
NMC27C512AN25	250

V_{CC} = 5V ± 10%

Parameter/Order Number	Access Time (ns)
NMC27C512AN150	150
NMC27C512AN170	170
NMC27C512AN200	200
NMC27C512AN250	250

Extended Temp Range (-40°C to +85°C)

V_{CC} = 5V ± 5%

Parameter/Order Number	Access Time (ns)
NMC27C512ANE15	150
NMC27C512ANE17	170
NMC27C512ANE20	200
NMC27C512ANE25	250

V_{CC} = 5V ± 10%

Parameter/Order Number	Access Time (ns)
NMC27C512ANE150	150
NMC27C512ANE170	170
NMC27C512ANE200	200
NMC27C512ANE250	250

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Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Temperature Under Bias -10°C to $+80^{\circ}\text{C}$
Storage Temperature -65°C to $+150^{\circ}\text{C}$

All Input Voltages except A9 and $\overline{\text{OE}}/\text{V}_{\text{PP}}$ with Respect to Ground (Note 9) $+6.5\text{V}$ to -0.6V

V_{CC} Supply Voltage with Respect to Ground $+7.0\text{V}$ to -0.6V

All Output Voltages with Respect to Ground (Note 9) $\text{V}_{\text{CC}} + 1$ to GND -0.6V

$\overline{\text{OE}}/\text{V}_{\text{PP}}$ Supply Voltage and A9 with Respect to Ground $+14.0\text{V}$ to -0.6V

Power Dissipation 1.0W
Lead Temperature (Soldering, 10 sec.) 300°C
ESD Rating (Mil Std. 883C, Method 3015.2) 2000V

Operating Conditions (Note 6)

Temperature Range 0°C to $+70^{\circ}\text{C}$

V_{CC} Power Supply
NMC27C512AN15, 17, 20, 25 $+5\text{V} \pm 5\%$
NMC27C512AN150, 170, 200, 250 $+5\text{V} \pm 10\%$

Temperature Range -40°C to $+85^{\circ}\text{C}$

V_{CC} Power Supply
NMC27C512ANE15, 17, 20, 25 $+5\text{V} \pm 5\%$
NMC27C512ANE150, 170, 200, 250 $+5\text{V} \pm 10\%$

READ OPERATION**DC Electrical Characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
I_{LI}	Input Load Current	$V_{\text{IN}} = \text{V}_{\text{CC}}$ or GND		0.01	1	μA
I_{LO}	Output Leakage Current	$V_{\text{OUT}} = \text{V}_{\text{CC}}$ or GND $\overline{\text{OE}} = V_{\text{IH}}$		0.01	1	μA
I_{CC1}	V_{CC} Current (Active) TTL Inputs	$\overline{\text{OE}} = V_{\text{IL}}$, $f = 5\text{ MHz}$ Inputs = V_{IH} or V_{IL} , $\text{I/O} = 0\text{ mA}$		10	30	mA
I_{CC2}	V_{CC} Current (Active) CMOS Inputs	$\overline{\text{OE}} = \text{GND}$, $f = 5\text{ MHz}$ Inputs = V_{CC} or GND, $\text{I/O} = 0\text{ mA}$		8	20	mA
I_{CCSB1}	V_{CC} Current (Standby) TTL Inputs	$\overline{\text{OE}} = V_{\text{IH}}$		0.1	1	mA
I_{CCSB2}	V_{CC} Current (Standby) CMOS Inputs	$\overline{\text{OE}} = \text{V}_{\text{CC}}$		0.5	100	μA
I_{PP}	V_{PP} Load Current	$\text{V}_{\text{PP}} = \text{V}_{\text{CC}}$			10	μA
V_{IL}	Input Low Voltage		-0.2		0.8	V
V_{IH}	Input High Voltage		2.0		$\text{V}_{\text{CC}} + 1$	V
V_{OL1}	Output Low Voltage	$I_{\text{OL}} = 2.1\text{ mA}$			0.4	V
V_{OH1}	Output High Voltage	$I_{\text{OH}} = -2.5\text{ mA}$	3.5			V
V_{OL2}	Output Low Voltage	$I_{\text{OL}} = 10\text{ }\mu\text{A}$			0.1	V
V_{OH2}	Output High Voltage	$I_{\text{OH}} = -10\text{ }\mu\text{A}$	$\text{V}_{\text{CC}} - 0.1$			V

AC Electrical Characteristics

Symbol	Parameter	Conditions	NMC27C512AN/ANE								Units
			15, 150		17, 170		20, 200		25, 250		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{ACC}	Address to Output Delay	$\overline{\text{CE}} = \overline{\text{OE}} = V_{\text{IL}}$		150		170		200		250	ns
t _{CE}	$\overline{\text{CE}}$ to Output Delay	$\overline{\text{OE}} = V_{\text{IL}}$		150		170		200		250	ns
t _{OE}	$\overline{\text{OE}}$ to Output Delay	$\overline{\text{CE}} = V_{\text{IL}}$		60		75		75		100	ns
t _{DF}	$\overline{\text{OE}}$ High to Output Float	$\overline{\text{CE}} = V_{\text{IL}}$	0	50	0	55	0	55	0	60	ns
t _{CF}	$\overline{\text{CE}}$ High to Output Float	$\overline{\text{OE}} = V_{\text{IL}}$	0	50	0	55	0	55	0	60	ns
t _{OH}	Output Hold from Addresses, $\overline{\text{CE}}$ or $\overline{\text{OE}}$, Whichever Occurred First	$\overline{\text{CE}} = \overline{\text{OE}} = V_{\text{IL}}$	0		0		0		0		ns

Capacitance $T_A = +25^\circ\text{C}$, $f = 1\text{ MHz}$ (Note 2)

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Symbol	Parameter	Conditions	Typ	Max	Units
C_{IN}	Input Capacitance Except \overline{OE}/V_{PP}	$V_{IN} = 0\text{V}$	5	10	pF
C_{OUT}	Output Capacitance	$V_{OUT} = 0\text{V}$	8	10	pF
C_{IN2}	\overline{OE}/V_{PP} Input Capacitance	$V_{IN} = 0\text{V}$	16	20	pF

AC Test Conditions

Output Load

1 TTL Gate and
 $C_L = 100\text{ pF}$ (Note 8)

Timing Measurement Reference Level

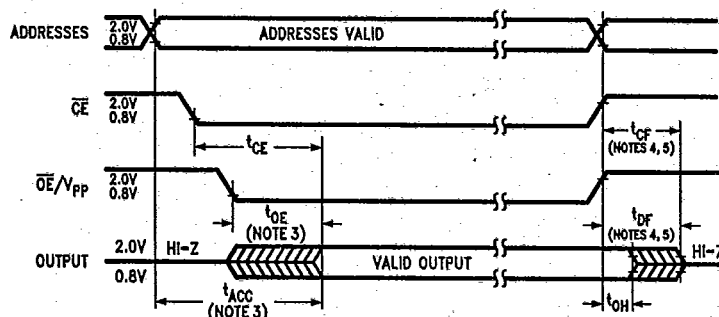
Inputs
Outputs0.8V and 2V
0.8V and 2V

Input Rise and Fall Times

 $\leq 5\text{ ns}$

Input Pulse Levels

0.45V to 2.4V

AC Waveforms (Notes 6, 7)

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Note 1: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note 2: This parameter is only sampled and is not 100% tested.

Note 3: \overline{OE} may be delayed up to $t_{ACC} - t_{OE}$ after the falling edge of \overline{CE} without impacting t_{ACC} .

Note 4: The t_{DF} and t_{CF} compare level is determined as follows:

High to TRI-STATE, the measured V_{OH1} (DC) -0.10V .

Low to TRI-STATE, the measured V_{OL1} (DC) $+0.10\text{V}$.

Note 5: TRI-STATE may be attained using \overline{OE} or \overline{CE} .

Note 6: The power switching characteristics of EPROMs require careful device decoupling. It is recommended that at least a $0.1\text{ }\mu\text{F}$ ceramic capacitor be used on every device between V_{CC} and GND.

Note 7: The outputs must be restricted to $V_{CC} + 1.0\text{V}$ to avoid latch-up and device damage.

Note 8: 1 TTL Gate: $I_{OL} = 1.6\text{ mA}$, $I_{OH} = -400\text{ }\mu\text{A}$.

CL: 100 pF includes fixture capacitance.

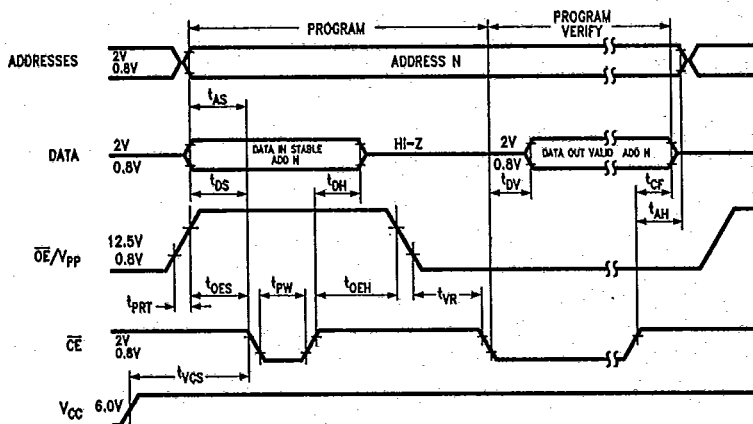
Note 9: Inputs and outputs can undershoot to -2.0V for 20 ns Max.

Programming Characteristics (Notes 1, 2, 3 and 4)

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Symbol	Parameter	Conditions	Min	Typ	Max	Units
t_{AS}	Address Setup Time		1			μs
t_{OES}	\overline{OE} Setup Time		1			μs
t_{DS}	Data Setup Time		1			μs
t_{AH}	Address Hold Time		0			μs
t_{DH}	Data Hold Time		1			μs
t_{CF}	Chip Enable to Output Float Delay	$\overline{OE} = V_{IL}$	0		60	ns
t_{PW}	Program Pulse Width		95	100	105	μs
t_{OEH}	\overline{OE} Hold Time		1			μs
t_{DV}	Data Valid from \overline{OE}	$\overline{OE} = V_{IL}$			250	ns
t_{PRT}	\overline{OE} Pulse Rise Time During Programming		50			ns
t_{VR}	V_{PP} Recovery Time		1			μs
I_{PP}	V_{PP} Supply Current During Programming Pulse	$\overline{OE} = V_{IL}$ $\overline{OE} = V_{PP}$			30	mA
I_{CC}	V_{CC} Supply Current				10	mA
T_A	Temperature Ambient		20	25	30	$^{\circ}C$
V_{CC}	Power Supply Voltage		6.0	6.25	6.5	V
V_{PP}	Programming Supply Voltage		12.5	12.75	13.0	V
t_{FR}	Input Rise, Fall Time		5			ns
V_{IL}	Input Low Voltage			0.0	0.45	V
V_{IH}	Input High Voltage		2.4	4.0		V
t_{IN}	Input Timing Reference Voltage		0.8	1.5	2.0	V
t_{OUT}	Output Timing Reference Voltage		0.8	1.5	2.0	V
t_{VCS}	V_{CC} Setup Time		1			μs

Programming Waveforms



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Note 1: National's standard product warranty applies only to devices programmed to specifications described herein.

Note 2: V_{CC} must be applied simultaneously or before V_{PP} and removed simultaneously or after V_{PP} . The EPROM must not be inserted into or removed from a board with voltage applied to V_{PP} or V_{CC} .

Note 3: The maximum absolute allowable voltage which may be applied to the V_{PP} pin during programming is 14V. Care must be taken when switching the V_{PP} supply to prevent any overshoot from exceeding this 14V maximum specification. At least a 0.1 μF capacitor is required across V_{CC} to GND to suppress spurious voltage transients which may damage the device.

Note 4: Programming and program verify are tested with the fast Program Algorithm at typical power supply voltages and timings.

Fast Programming Algorithm Flow Chart (Note 4)

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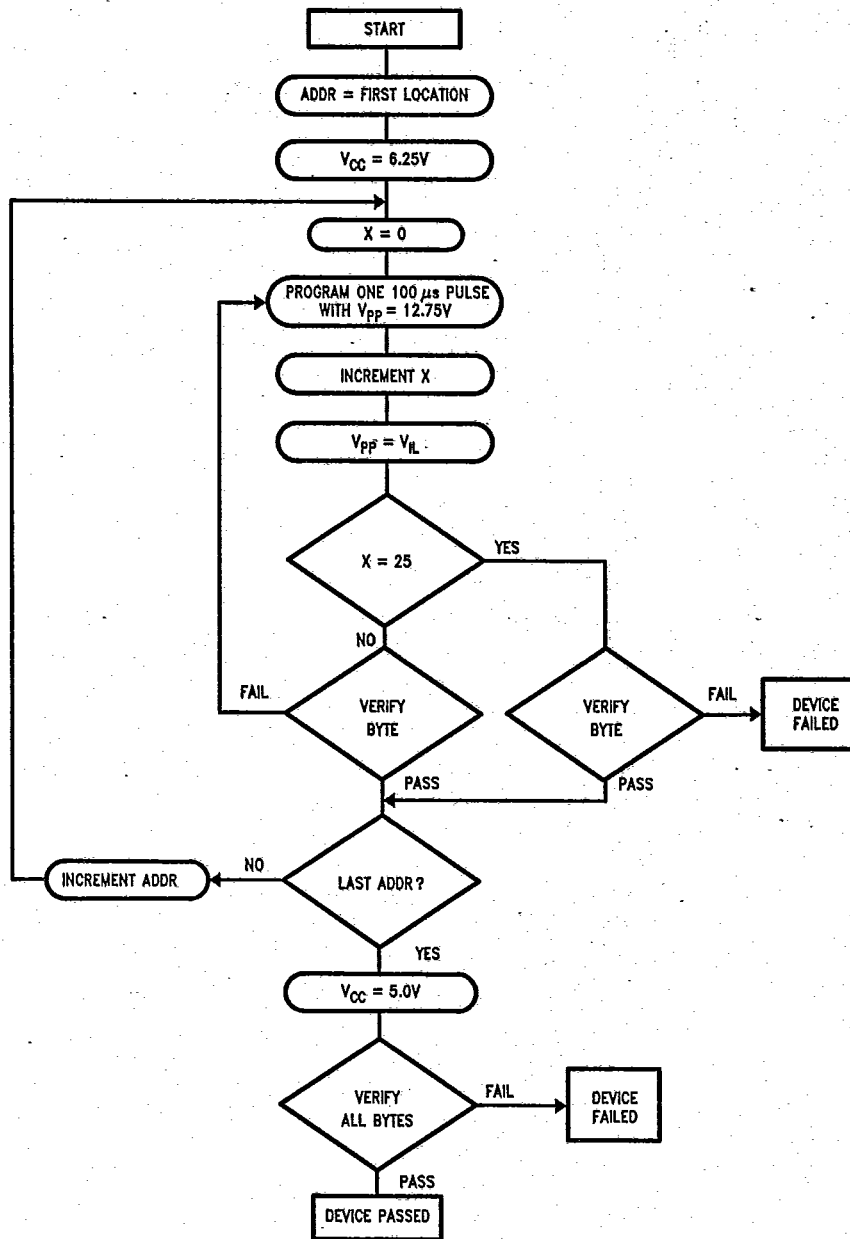


FIGURE 1

TL/D/8754-5

Interactive Programming Algorithm Flow Chart (Note 4)

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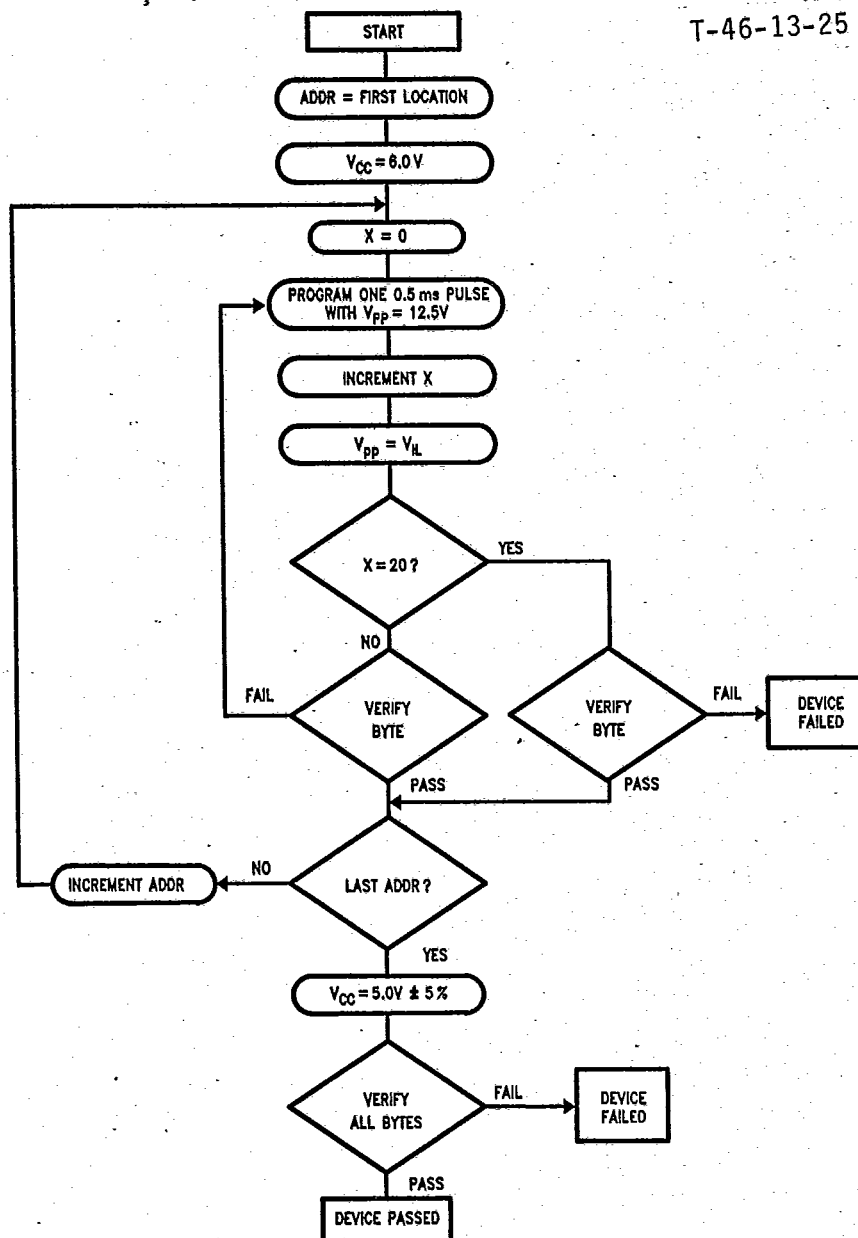


FIGURE 2

TL/D/8754-8

Functional Description

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DEVICE OPERATION

The six modes of operation of the NMC27C512AN are listed in Table I. A single 5V power supply is required in the read mode. All inputs are TTL levels except for \overline{OE}/V_{PP} during programming. In the program mode the \overline{OE}/V_{PP} input is pulsed from a TTL low level to 12.75V.

Read Mode

The NMC27C512AN has two control functions, both of which must be logically active in order to obtain data at the outputs. Chip Enable (\overline{CE}) is the power control and should be used for device selection. Output Enable (\overline{OE}) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that addresses are stable, address access time (t_{ACC}) is equal to the delay from \overline{CE} to output (t_{CE}). Data is available at the outputs after the falling edge of \overline{OE} , assuming that \overline{CE} has been low and addresses have been stable for at least $t_{ACC} - t_{OE}$.

The sense amps are clocked for fast access time. V_{CC} should therefore be maintained at operating voltage during read and verify. If V_{CC} temporarily drops below the spec. voltage (but not to ground) an address transition must be performed after the drop to ensure proper output data.

Standby Mode

The NMC27C512AN has a standby mode which reduces the active power dissipation by over 99%, from 110 mW to 0.55 mW. The NMC27C512AN is placed in the standby mode by applying a CMOS high signal to the \overline{CE} input. When in standby mode, the outputs are in a high impedance state, independent of the \overline{OE} input.

Output OR-Tying

Because EPROMs are usually used in larger memory arrays, National has provided a 2-line control function that accommodates this use of multiple memory connection. The 2-line control function allows for:

- the lowest possible memory power dissipation, and
- complete assurance that output bus contention will not occur.

To most efficiently use these two control lines, it is recommended that \overline{CE} (pin 20) be decoded and used as the primary device selecting function, while \overline{OE}/V_{PP} (pin 22) be made a common connection to all devices in the array and connected to the READ line from the system control bus. This assures that all deselected memory devices are in their low power standby modes and that the output pins are active only when data is desired from a particular memory device.

Programming

CAUTION: Exceeding 14V on pin 22 (\overline{OE}/V_{PP}) will damage the NMC27C512AN.

Initially, and after each erasure, all bits of the NMC27C512AN are in the "1" state. Data is introduced by selectively programming "0s" into the desired bit locations. Although only "0s" will be programmed, both "1s" and "0s" can be presented in the data word. The only way to change a "0" to a "1" is by ultraviolet light erasure.

The NMC27C512AN is in the programming mode when \overline{OE}/V_{PP} is at 12.75V. It is required that at least a 0.1 μ F capacitor be placed across V_{CC} and ground to suppress spurious voltage transients which may damage the device. The data to be programmed is applied 8 bits in parallel to the data output pins. The levels required for the address and data inputs are TTL.

When the address and data are stable, an active low, TTL program pulse is applied to the \overline{CE} input. A program pulse must be applied at each address location to be programmed. The NMC is programmed with the Fast Programming Algorithm shown in Figure 1. Each Address is programmed with a series of 100 μ s pulses until it verifies good, up to a maximum of 25 pulses. Most memory cells will program with a single 100 μ s pulse.

Note: Some programmer manufacturers due to equipment limitation may offer Interactive program Algorithm (shown in Figure 2).

The NMC27C512AN must not be programmed with a DC signal applied to the \overline{CE} input.

Programming multiple NMC27C512As in parallel with the same data can be easily accomplished due to the simplicity of the programming requirements. Like inputs of the paralleled NMC27C512AN may be connected together when they are programmed with the same data. A low level TTL pulse applied to the \overline{CE} input programs the paralleled NMC27C512AN.

The NMC27C512AN is packaged in a plastic molded package which does not have a transparent lid. Therefore the memory cannot be erased. This means that after a user has programmed a memory cell to a "0" it cannot be changed back to a "1".

If an application requires erasing and reprogramming, the NMC27C512AQ UV Erasable PROM in a windowed package should be used.

PROGRAM INHIBIT

Programming multiple NMC27C512ANs in parallel with different data is also easily accomplished. Except for \overline{CE} all like inputs (including \overline{OE}) of the parallel NMC27C512AN may be common. A TTL low level program pulse applied to

TABLE I. Mode Selection

Pins	\overline{CE} (20)	\overline{OE}/V_{PP} (22)	V_{CC} (28)	Outputs (11-13, 15-19)
Mode				
Read	V_{IL}	V_{IL}	5.0V	D_{OUT}
Standby	V_{IH}	Don't Care	5.0V	Hi-Z
Output Disable	Don't Care	V_{IH}	5.0V	Hi-Z
Program	V_{IL}	12.75V	6.25V	D_{IN}
Program Verify	V_{IL}	V_{IL}	6.25V	D_{OUT}
Program Inhibit	V_{IH}	12.75V	6.25V	Hi-Z

Functional Description (Continued)

an NMC27C512A's \overline{CE} input with \overline{OE}/V_{PP} at 12.75V will program that NMC27C512AN. A TTL high level \overline{CE} input inhibits the other NMC27C512A from being programmed.

PROGRAM VERIFY

A verify should be performed on the programmed bits to determine whether they were correctly programmed. The verify is accomplished with \overline{OE}/V_{PP} and \overline{CE} at V_{IL} . Data should be verified t_{PV} after the falling edge of \overline{CE} .

MANUFACTURER'S IDENTIFICATION CODE

The NMC27C512AN has a manufacturer's identification code to aid in programming. The code, shown in Table II, is two bytes wide and is stored in a ROM configuration on the chip. It identifies the manufacturer and the device type. The code for NMC27C512AN is "8F 85", where "8F" designates that it is made by National Semiconductor, and "85" designates a 512k part.

The code is accessed by applying 12V ± 0.5 V to address pin A9. Addresses A1–A8, A10–A15, \overline{CE} and \overline{OE} are held at V_{IL} . Address A0 is held at V_{IL} for the manufacturer's code, and at V_{IH} for the device code. The code is read out on the eight data pins. Proper code access is only guaranteed at 25°C $\pm 5^\circ$ C.

The primary purpose of the manufacturer's identification code is automatic programming control. When the device is

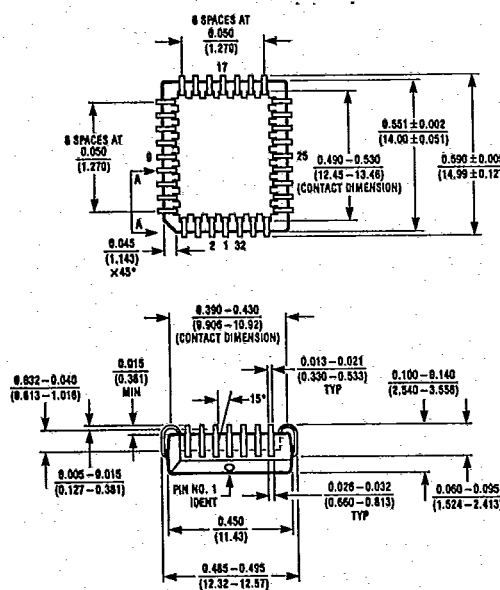
inserted in an EPROM programmer socket, the programmer reads the code and then automatically calls up the specific programming algorithm for the part. This automatic programming control is only possible with programmers which have the capability of reading the code.

SYSTEM CONSIDERATION

The power switching characteristics of EPROMs require careful decoupling of the devices. The supply current, I_{CC} , has three segments that are of interest to the system designer—the standby current level, the active current level, and the transient current peaks that are produced by voltage transitions on input pins. The magnitude of these transient current peaks is dependent on the output capacitance loading of the device. The associated V_{CC} transient voltage peaks can be suppressed by properly selected decoupling capacitors. It is recommended that at least a 0.1 μ F ceramic capacitor be used on every device between V_{CC} and GND. This should be a high frequency capacitor of low inherent inductance. In addition, at least a 4.7 μ F bulk electrolytic capacitor should be used between V_{CC} and GND for each eight devices. The bulk capacitor should be located near where the power supply is connected to the array. The purpose of the bulk capacitor is to overcome the voltage drop caused by the inductive effects of the PC board traces.

TABLE II. Manufacturer's Identification Code

Pins	A ₀ (10)	O ₇ (19)	O ₆ (18)	O ₅ (17)	O ₄ (16)	O ₃ (15)	O ₂ (13)	O ₁ (12)	O ₀ (11)	Hex Data
Manufacturer Code	V_{IL}	1	0	0	0	1	1	1	1	8F
Device Code	V_{IH}	1	0	0	0	0	1	0	1	85

Package Information

32-Lead PLCC Package
Order Number NMC27C512AV

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